

EV GROUP BRINGS HIGH-SPEED HIGH-PRECISION METROLOGY TO 3D HETEROGENEOUS INTEGRATION – November 17, 2021

EVG today unveiled the EVG®40 NT2 automated metrology system, which provides overlay and critical dimension (CD) measurements for wafer-to-wafer (W2W), die-to-wafer (D2W) and die-to-die (D2D) bonding as well as maskless lithography applications. Designed for high-volume production with feedback loops for real-time process correction and optimization, the EVG40 NT2 helps device manufacturers, foundries and packaging houses accelerate the introduction of new 3D/heterogeneous integration products as well as improve yields and avoid scrapping of highly valuable wafers.



The screenshot shows a news article from China Tech Bao. The header includes the logo and website address. The main title is "EV Group推出3D异构集成高速高精度计量系统". Below it, there's a sub-headline: "EVG40 NT2具有突破性计量性能，有助于加快晶圆级和晶片混合键合及无掩模光刻的实施". The article text discusses the system's capabilities for W2W, D2W, and D2D bonding, as well as maskless lithography. It highlights its speed and precision, and how it supports real-time process correction and optimization. The sidebar features a "栏目排行" (Column Ranking) with several links, a "相关标签" (Related Tags) section with terms like "芯片", "IC", "封装", etc., and a "内容推荐" (Content Recommendation) section with thumbnail images and titles of other articles.